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JP2000299360A2: SHEET-TYPE SEMICONDUCTOR IC WAFER DIRECT CONDUCTION TEMPERATURE-TESTING DEVICE

Title:

Country:

JP Japan

Kind:

A2 Document Laid open to Public inspection

Inventor(s):

MORIWAKI IKURO

Applicant/Assignee



DOU YEE JAPAN CO LTD

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Issued/Filed Dates:

Oct. 24, 2000 / April 13, 1999

Application Number:

JP1999000140541

IPC Class:

H01L 21/66:

Priority Number(s):

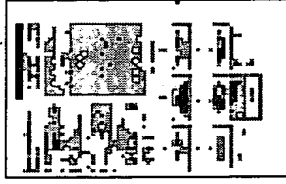
April 13, 1999 JP1999000140541

Abstract:

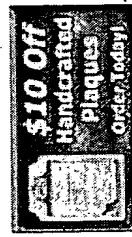
Problem to be solved: To perform day-to-day conduction high temperature shelf test at a low cost by applying pressure to a semiconductor IC wafer and a wafer probe pin module in a contacting direction, and by heating and cooling each of the semiconductor IC wafer and the wafer probe pin module by an individual temperature control system.

Solution: In a chamber 6, a wafer 1 to be inspected which is tentatively locked by a chuck holder 4 and a probe pin module 2 are pinched between upper and lower parts by a heating block 3, and are further pressed by a press 7 so that the entire probe pin 2 is completely brought into contact with a wafer to be tested. Then, after the entire probe pin 2 is brought into contact with the bump of the wafer 1 to be inspected, a required power supply and a signal are applied from a power supply/signal source 8 for carrying out a heating/cooling conduction shelf test, thus easily performing day-to-

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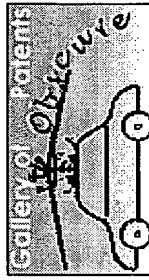
day conduction high temperature shelf test of many elements at a low cost.

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Family: [Show known family members](#)

Other Abstract Info: none

Foreign References: No patents reference this one



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